

## ■ Features

- 0.2 inch single color display
- Long lifetime operation
- IC compatible
- Low power dissipation
- Black surface with white segment

## ■ Applications

- Counting device
- Home and smart appliances

## ■ Absolute Maximum Rating (Ta=25°C)

| Item                                                 | Symbol          | Value      |     | Unit |
|------------------------------------------------------|-----------------|------------|-----|------|
|                                                      |                 | YG/Y/R     | B/G |      |
| DC Forward Current                                   | I <sub>F</sub>  | 25         | 25  | mA   |
| Pulse Forward Current#                               | I <sub>FP</sub> | 100        | 100 | mA   |
| Reverse Voltage                                      | V <sub>R</sub>  | 5          | 5   | V    |
| Power Dissipation                                    | P <sub>t</sub>  | 62.5       | 72  | mW   |
| Operating Temperature                                | Topr            | -30 ~ +70  |     | °C   |
| Storage Temperature                                  | Tstg            | -40~ +85   |     | °C   |
| Lead Soldering Temperature(1.6mm from seating plane) | Tsol            | 260°C/5sec |     | °C   |

#Pulse width Max.10ms Duty ratio max 1/10

## ■ Electrical -Optical Characteristics (Ta=25°C)

| Part Number | Color        |    |                                                                                     | V <sub>F</sub> (V)*  |      |      | I <sub>R</sub> (μA) | I <sub>v</sub> (mcd)* |      |      | λD(nm)* |      |      |
|-------------|--------------|----|-------------------------------------------------------------------------------------|----------------------|------|------|---------------------|-----------------------|------|------|---------|------|------|
|             |              |    |                                                                                     | Min.                 | Typ. | Max. | Max.                | Min.                  | Typ. | Max. | Min.    | Typ. | Max. |
|             |              |    |                                                                                     | I <sub>F</sub> =20mA |      |      | V <sub>R</sub> =5V  | I <sub>F</sub> =20mA  |      |      |         |      |      |
| OSX10201-B  | Blue         | B  |  | -                    | 3.3  | 3.6  | 20                  | -                     | 50   | -    | 460     | 465  | 475  |
| OSX10201-G  | Pure Green   | G  |  | -                    | 3.1  | 3.6  | 20                  | -                     | 262  | -    | 515     | 525  | 530  |
| OSX10201-YG | Yellow Green | YG |  | -                    | 2.1  | 2.5  | 20                  | -                     | 15   | -    | 565     | 570  | 575  |
| OSX10201-Y  | Yellow       | Y  |  | -                    | 2.1  | 2.5  | 20                  | -                     | 133  | -    | 585     | 587  | 595  |
| OSX10201-R  | Red          | R  |  | -                    | 2.1  | 2.5  | 20                  | -                     | 70   | -    | 620     | 630  | 635  |

\*1 Tolerance of measurements of dominant wavelength is ±1nm

\*2 Tolerance of measurements of luminous intensity is ±15%

\*3 Tolerance of measurements of forward voltage is ±0.1V

## ■ Package Dimensions and Pin Function

### OSX10201-X

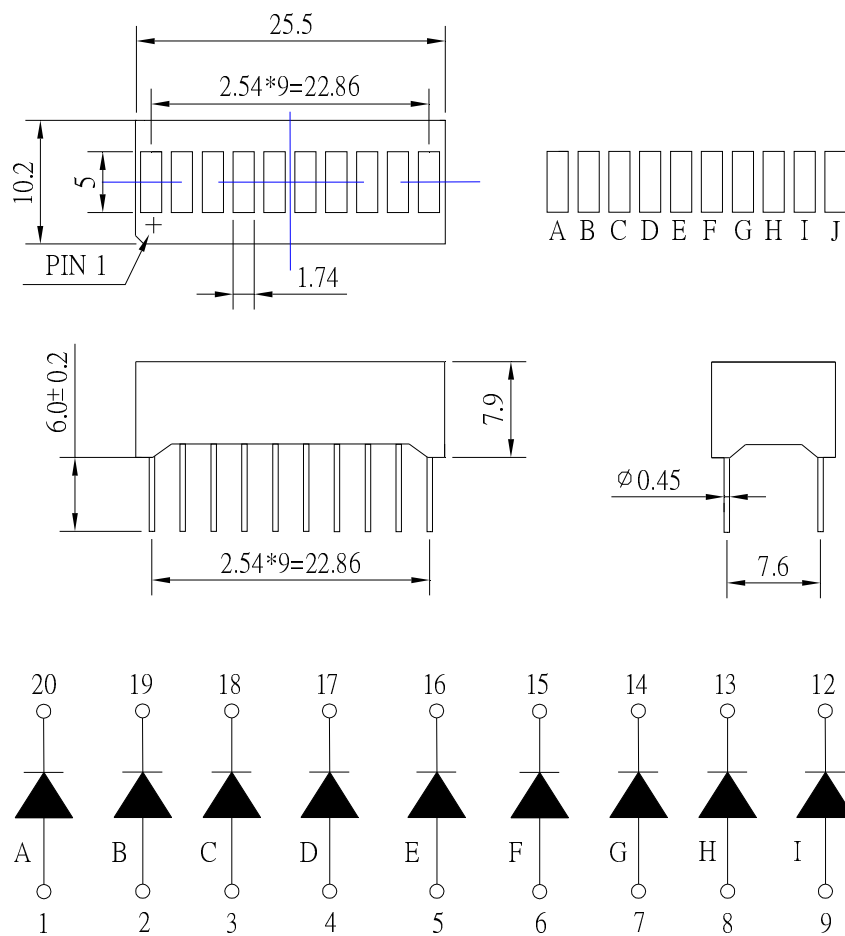
Note:

1, Unit : mm (Tolerance:  $\pm 0.25$ mm unless

otherwise noted)

2, The slope angle of any PIN

may be  $\pm 5.0^\circ$  Max



## LAMP APPLICATION (PB FREE SOLDERJING)

Apply to Display (DIP) SERIES.

### Description:

#### (1) Manual soldering (Solder Iron)

- (1.1) Temperature at tip of the iron: 350°C Max.
- (1.2) It's banned to load any stress on the resin during soldering.
- (1.3) Soldering time: 3sec.Max.(one time only.)
- (1.4) Leave 3mm of minimum distance from the base of the epoxy.

#### (2) Dip Soldering (Wave Soldering-Solder Bath)

- (2.1) Leave 3mm of minimum distance from the base of the epoxy.  
Soldering beyond the base of the tie bar (stand off) is recommended.
- (2.2) When soldering, do not put stress on the Display during heating.
- (2.3) Cutting the lead frames at high temperatures may cause LED failure.
- (2.4) Never take next process until the component is cooled down to room temperature after reflow.
- (2.5) After soldering, do not warp the circuit board.
- (2.6) The recommended dip soldering profile is the following.

